

WHAT IS CLAIMED IS

*at A1*  
1. An electronic circuit device including a plurality of circuit boards which have electronic parts mounted thereon and are three-dimensionally assembled, characterized in that said plural circuit boards are stacked in the thickness direction through metal pieces at least one ends of which are fixed to the circuit boards.

2. The electronic circuit device as claimed in claim 1, wherein both ends of each metal piece are fixed to said circuit boards at both the *sides* thereof by materials which are different in melting point.

*at A2*  
3. An electronic circuit device including a plurality of circuit boards which have electronic parts mounted thereon and are three-dimensionally assembled, characterized in that said plural circuit boards are assembled in the thickness direction through spacers each of which comprises a metal piece, and one end of each metal piece is fixed to one circuit board by solder while the other end of said metal piece is fixed to another circuit board by adhesive agent having a melting point lower than the solder.

4. The electronic circuit device as claimed in claim 3, wherein said adhesive agent is conductive adhesive agent, and said circuit boards are electrically connected to each other by said metal pieces.

5. An electronic circuit device including a plurality of

circuit boards which have electronic parts mounted thereon and are three-dimensionally assembled, characterized in that said plural circuit boards are assembled in the thickness direction through spacers each of which comprises a metal piece, and both the ends of each metal piece are fixed to said circuit boards at both the sides of the metal piece by solder.

6. The electronic circuit device as claimed in claim 5, wherein both the ends of each metal piece are soldered to said circuit boards at both the sides thereof by the solder materials which are different in melting point.

7. The electronic circuit device as claimed in claim 6, wherein said electronic parts are soldered to said circuit boards by solder material having the same melting point as the solder material having a higher melting point in said solder materials used to fix both the ends of said metal pieces to said circuit boards.